

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	@ad< "20040928" and underfill and (solde\$6 resist) and decal	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:07
L3	78	@ad< "20040928" and underfill and decal	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:07
L4	74	@ad< "20040928" and underfill and decal and solder	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:08
L5	11	@ad< "20040928" and underfill and decal and (solder (resist or mask))	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:08
L6	724	@ad< "20040928" and underfill and (solder (resist or mask)) and semiconductor	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:13
L7	0	@ad< "20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (functional (surface or side))	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:43
L8	0	@ad< "20040928" and underfill and (solde\$6 (resist or mask)) and (functional (surface or side))	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:43
L9	46	@ad< "20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (circuitry)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:44
L10	5	@ad< "20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (chip circuitry)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:44
L11	4	@ad< "20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (chip connect)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:46

L12	44	@ad<"20040928" and murali-venkatesan.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:57
L13	0	@ad<"20040928" and sunohara-mashiro.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/04 09:59
L14	26	@ad<"20040928" and sunohara-masahiro.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/04 10:00
L15	1	@ad<"20040928" and "257/778".ocls. and underfill and (solde\$6 (resist or mask)) and (c4 package)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 10:03
L16	23	@ad<"20040928" and "257/778".ocls. and underfill and (solde\$6 (resist or mask)) and (c4)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 10:04
S1	2730	@ad<"20040928" and "257/778".ocls.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:53
S2	669	@ad<"20040928" and "257/778".ocls. and underfill	US-PGPUB; USPAT	ADJ	ON	2008/12/03 16:11
S3	42	@ad<"20040928" and "257/778".ocls. and underfill and (solde\$6 resist)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 16:11
S4	38	tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:31
S5	26	tanida-kazumasa.in. and (seal or seal\$4)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:32
S6	26	tanida-kazumasa.in. and (seal or seal\$4) and surface	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:33
S7	18	tanida-kazumasa.in. and (seal or seal\$4) and surface and (open or opening)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:34
S8	18	tanida-kazumasa.in. and (seal or seal\$4) and surface and (open or opening or opened)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:37

S9	0	"miyata-osamu.in" and (seal or seal\$4) and surface and (open or opening or opened) not tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:51
S10	14	miyata-osamu.in. and (seal or seal\$4) and surface and (open or opening or opened) not tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:51
S11	432	rohm.as. and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:01
S12	152	rohm.as. and semiconductor and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:02
S13	86	rohm.as. and (semiconductor device) and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:04
S14	7	rohm.as. and fill and (semiconductor device) and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:05
S15	16	rohm.as. and (semiconductor device) and (seal or seal\$4) and surface and ("open.clm" or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:06

S16	28	roh.m.as. and (semiconductor) and (seal or seal\$4) and surface and ("open.clm" or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:07
S17	30	roh.m.as. and (semiconductor) and (seal or seal\$4) and surface and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:07
S18	23	roh.m.as. and (semiconductor) and (seal or seal\$4) and surface.clm. and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:07
S19	19	roh.m.as. and (semiconductor.clm.) and (seal or seal\$4) and surface.clm. and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:07

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